

# Stannopure<sup>®</sup> HSB

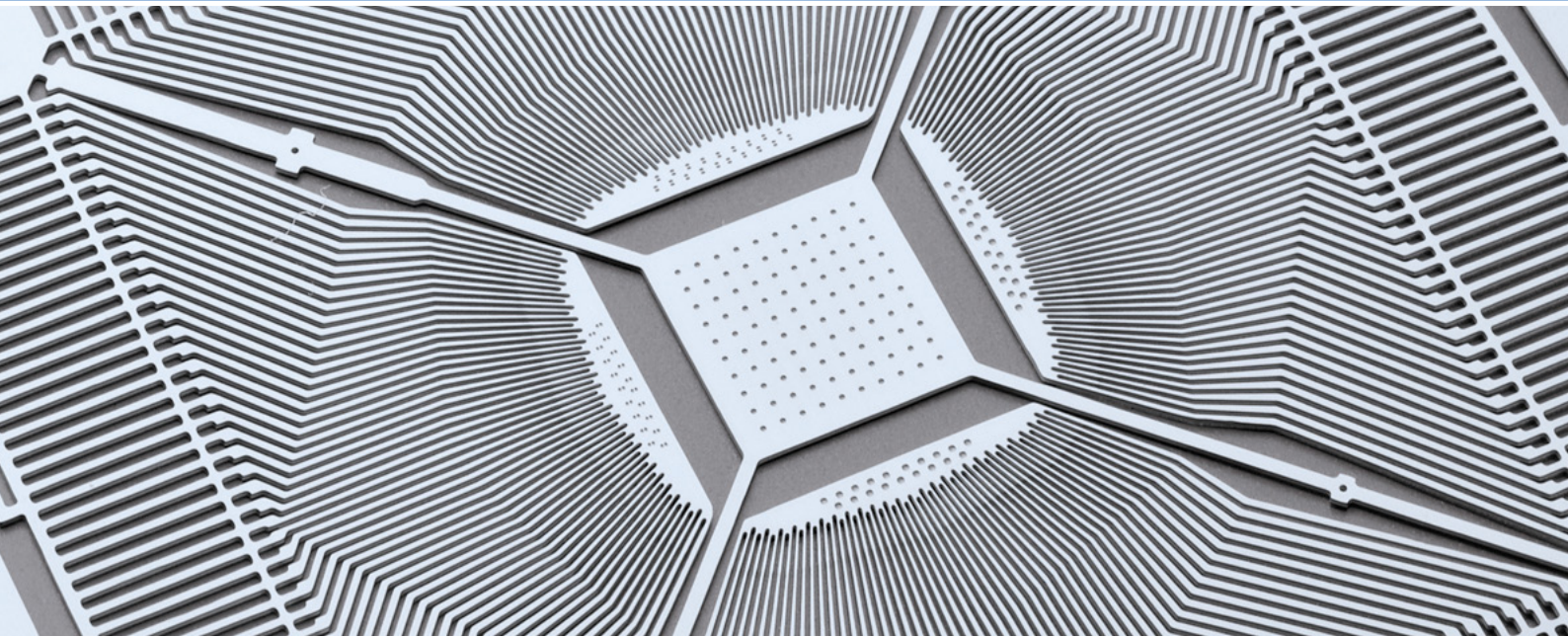
Bright electrolytic tin process



Electronics

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## StannoPure<sup>®</sup> HSB – Best bright tin in the market

### StannoPure<sup>®</sup> HSB

is a versatile pure bright tin plating process that creates deposits with excellent solderability and wettability. The process is qualified and recognized internationally by major manufacturers for bus bars, connectors, and lead frame packages.

StannoPure<sup>®</sup> HSB is suitable for any tool type. Due to the use of an MSA-based electrolyte, the highest current densities can be achieved leading to higher deposition rates. In addition, the electrolyte exhibits a long bath life and little maintenance and provides easy and cost-effective wastewater treatment.

### Properties

- Current density range: 1 – 50 ASD
- Applicable to all tools
- Excellent solderability
- Purity: > 99.90 %
- Low whisker propensity
- High-speed and low-speed applications

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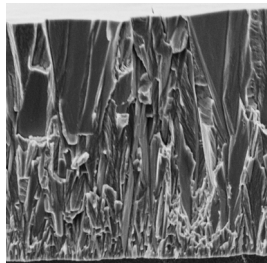


Figure 1:  
Microscopic view of  
StannoPure<sup>®</sup> HSB deposits

## Technology in detail

Stannopure<sup>®</sup> HSB operates in all tools - in high-speed as well as in rack and barrel. The MSA based electrolyte is known for its low levels of Stannic tin (Sn(IV)) and a low co-deposition of organics. Thereby, StannoPure<sup>®</sup> HSB is very insensitive to handling and fulfilling JESD201, Class 2 products.

StannoPure<sup>®</sup> HSB features a carrier and a brightener additive. The carrier contains essential surfactants and antioxidants to suppress the formation of stannic tin. It enables a smooth deposition and a wide concentration window and counteracts a brightener overdose. The brightener contains the necessary brightener blend to enable a wide current density operation thereby allowing a fully bright tin surface.

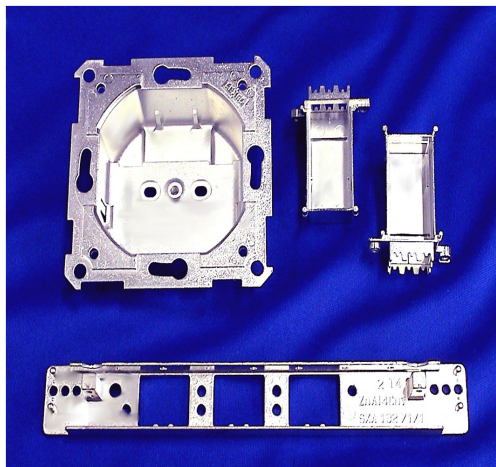


Figure 2+3: StannoPure<sup>®</sup> HSB plated as final finish

